

## Electronic Patent Application Fee Transmittal

<b>Application Number:</b>	10570665			
<b>Filing Date:</b>	06-Mar-2006			
<b>Title of Invention:</b>	Bonded wafer and its manufacturing method			
<b>First Named Inventor/Applicant Name:</b>	Akihiko Endo			
<b>Filer:</b>	Arnold Turk/Victoria Schubert			
<b>Attorney Docket Number:</b>	P29120			
Filed as Large Entity				
<b>U.S. National Stage under 35 USC 371 Filing Fees</b>				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Basic Filing:</b>				
<b>Pages:</b>				
<b>Claims:</b>				
<b>Miscellaneous-Filing:</b>				
<b>Petition:</b>				
<b>Patent-Appeals-and-Interference:</b>				
<b>Post-Allowance-and-Post-Issuance:</b>				
<b>Extension-of-Time:</b>				
Extension - 2 months with \$0 paid	1252	1	490	490

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Total in USD (\$)				490